

PRODUCT/PROCESS CHANGE NOTIFICATION (PCN)

PCN #: A082100-1 Date: 08/2 Product Affected: PCI9052 Manufacturing Location Affected: Taiwan Date Effective: 08/01/00 Contact: Ted Rudolph Title: Quality Engineering Manager Phone: 408-328-3530 Fax #: 408-732-5916 E-mail: qa@plxtech.com	MEANS OF DISTINGUISHING CHANGED DEVICES Product Mark Y Back Mark Date Code Y Other Additional Data: N/A Samples: N/A
DESCRIPTION AND PURPOSE OF CHA	ANGE:
Y Die Technology	
■ Wafer Fabrication process	
Y Assembly Process	Due to capacity constraints, PLX has qualified TSMC's Fab 9. This
■ Equipment	additional fab capacity will give PLX more flexibility in the manufacture
Y Material	of its PCI9052 to meet the increasing demands from our customers.
Y Testing	The current fab (F2) is a 6" wafer fab, and the additional fab (F9) is a
■ Manufacturing Site	8" wafer fab. Consequently, in the future, the PCI9052 may be
Y Data Sheet	manufactured in either fab. Part marking will identify the fab origin.
Customer:	Y Approval for shipments prior to effective date.
Name/Date:	E-Mail Address:
Title:	Phone# /Fax# :
Customer Comments:	
REC'D. BY:	DATE: